

TM Forum Integration Program Maintenance, Protection and Alarm Control

Release Notes for Release 1.0

TIP_MPAC_RN

Version 1.1



September 2011

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Executive Summary

This document constitutes the Release Notes of the TM Forum Integration Program (TIP) Maintenance, Protection and Alarm Control (MPAC) Interface.

It presents a brief overview of MPAC and it shows the contents of the specification package.

This document is part of the MPAC release kit. The entire kit can be found on the TM Forum web site.

1 Overview of MPAC

Harmonization work has been done on Alarm Management within TM Forum between OSS/J Fault Management API and MTOSI Resource Trouble Management DDP leading to the definition of the Resource Alarm Management (RAM) interface. For a true harmonization, it is needed to be able to phase out existing Fault Management interfaces from OSS/J and MTOSI when introducing the new one to avoid creating yet another FM interface.

During the initial migration discussions it was noted that the scope of MTOSI Resource Trouble Management DDP is slightly larger than the scope of RAM, which is only covering the Alarm Collection and Handling parts of RTM.

In order to complete the coverage of MTOSI RTM DDP and ease the migration to RAM, the missing pieces of RTM have been gathered in the Maintenance, Protection and Alarm Control (MPAC) interface.

The scope of the MPAC interface covers the following MTOSI Service Interfaces, which are part of the MTOSI RTM DDP:

- Alarm Control
- ASAP Control
- ASAP Retrieval
- Maintenance Control
- Protection Control
- Protection Retrieval

2 Changes in this release

This section describes the major changes in this release.

As this is the initial release of MPAC, this section is left empty intentionally.

3 Release Definition

This section describes the contents of the TIP MPAC specification package.

3.1 Specification Package Structure

All files in the zip package are stored under the top directory TIP_MPAC_Specification_V1.0.0

It contains the following sub-directories:

- Business_Agreement
- Information_Agreement
- Information_Agreement \ models
- Interface_Implementation_Specifications \ WSDL
- Supporting_Material

Release Notes (this document) and license file are directly stored under the top directory of the kit.

3.2 Business Agreement

The directory Business_Agreement contains the latest MPAC Business Agreement document:

TMF_MPAC_BA_V1.2 as .doc and .pdf

3.3 Information Agreement

The directory Information_Agreement contains the MPAC Information Agreement document generated from the Tigerstripe model: TIP_IA_MPAC_V1.0.pdf.

The directory Information_Agreement \ models contains the modules associated with this project. The Tigerstripe modules are read-only versions of the model that can be used and referenced by other projects. This directory contains the following modules:

- org.tmforum.tip.mpac_1.0.zip : the module corresponding to the TIP MPAC model
- org.tmforum.tip.mpac.dep _1.0.zip : the module corresponding to the dependencies needed by the TIP MPAC model

3.4 Interface Implementation Specifications

The directory Interface_Implementation_Specifications \ WSDL contains the generated XSD and WSDL for the MPAC interface.

3.5 Supporting Material

The directory Supporting_Material contains the following files:

- MigrationfromRTM_to_TIP.xls that provides the migration mapping from MTOSI RTM to TIP RAM and MPAC
- SD1-29_PGPParameters.doc: this supporting document coming from MTOSI is listing the PGP Parameters.
- SD1-34_protectionSwitch.doc: this supporting document coming from MTOSI is providing details on Protection Switching.

4 Administrative Appendix

4.1 Document History

Version History (This document)

Version Number	Date Modified	Modified by:	Description of changes
1.0	September 2011	Marc Flauw	Initial version
1.1	October 2011	Alicja Kawecki	Corrected Notice p. 2 and reference to MPAC BA in Section 3.2, deleted Section 4.3 About TM Forum

Release History (MPAC Release)

1.0	September 2011	RSA team	Initial version
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4.2 Company Contact Details

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4.3 Acknowledgments

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